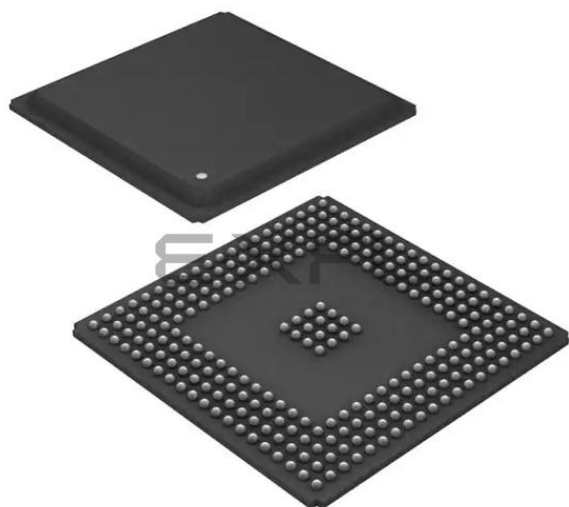




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	2560
Number of I/O	202
Number of Gates	54000
Voltage - Supply	3V ~ 3.6V, 4.75V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	272-BBGA
Supplier Device Package	272-PBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a42mx36-bg272

Tables

Table 1	Product profile	1
Table 2	Plastic Device Resources	4
Table 3	Ceramic Device Resources	4
Table 4	Temperature Grade Offerings	5
Table 5	Speed Grade Offerings	5
Table 6	Voltage Support of MX Devices	13
Table 7	Fixed Capacitance Values for MX FPGAs (pF)	16
Table 8	Device Configuration Options for Probe Capability	17
Table 9	Test Access Port Descriptions	18
Table 10	Supported BST Public Instructions	18
Table 11	Boundary Scan Pin Configuration and Functionality	19
Table 12	Absolute Maximum Ratings for 40MX Devices*	20
Table 13	Absolute Maximum Ratings for 42MX Devices*	20
Table 14	Recommended Operating Conditions	21
Table 15	5V TTL Electrical Specifications	21
Table 16	Absolute Maximum Ratings for 40MX Devices*	22
Table 17	Absolute Maximum Ratings for 42MX Devices*	22
Table 18	Recommended Operating Conditions	22
Table 19	3.3V LVTTTL Electrical Specifications	23
Table 20	Absolute Maximum Ratings*	23
Table 21	Recommended Operating Conditions	24
Table 22	Mixed 5.0V/3.3V Electrical Specifications	25
Table 23	DC Specification (5.0 V PCI Signaling)	25
Table 24	AC Specifications (5.0V PCI Signaling)*	26
Table 25	DC Specification (3.3 V PCI Signaling)	27
Table 26	AC Specifications for (3.3 V PCI Signaling)*	27
Table 27	Package Thermal Characteristics	29
Table 28	42MX Temperature and Voltage Derating Factors (Normalized to $T_J = 25^{\circ}\text{C}$, $V_{CCA} = 5.0\text{ V}$)	38
Table 29	40MX Temperature and Voltage Derating Factors(Normalized to $T_J = 25^{\circ}\text{C}$, $V_{CC} = 5.0\text{ V}$)	38
Table 30	42MX Temperature and Voltage Derating Factors(Normalized to $T_J = 25^{\circ}\text{C}$, $V_{CCA} = 3.3\text{ V}$)	39
Table 31	40MX Temperature and Voltage Derating Factors (Normalized to $T_J = 25^{\circ}\text{C}$, $V_{CC} = 3.3\text{ V}$)	39
Table 32	Clock Specification for 33 MHz PCI	40
Table 33	Timing Parameters for 33 MHz PCI	40
Table 34	A40MX02 Timing Characteristics (Nominal 5.0 V Operation)	41
Table 35	A40MX02 Timing Characteristics (Nominal 3.3 V Operation)	43
Table 36	A40MX04 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $V_{CC} = 4.75\text{ V}$, $T_J = 70^{\circ}\text{C}$)	46
Table 37	A40MX04 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $V_{CC} = 3.0\text{ V}$, $T_J = 70^{\circ}\text{C}$)	49
Table 38	A42MX09 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $V_{CCA} = 4.75\text{ V}$, $T_J = 70^{\circ}\text{C}$)	52
Table 39	A42MX09 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $V_{CCA} = 3.0\text{ V}$, $T_J = 70^{\circ}\text{C}$)	56
Table 40	A42MX16 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $V_{CCA} = 4.75\text{ V}$, $T_J = 70^{\circ}\text{C}$)	60
Table 41	A42MX16 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $V_{CCA} = 3.0\text{ V}$, $T_J = 70^{\circ}\text{C}$)	64
Table 42	A42MX24 Timing Characteristics (Nominal 5.0 V Operation) (Worst-Case Commercial Conditions, $V_{CCA} = 4.75\text{ V}$, $T_J = 70^{\circ}\text{C}$)	67
Table 43	A42MX24 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions, $V_{CCA} = 3.0\text{ V}$, $T_J = 70^{\circ}\text{C}$)	71
Table 44	A42MX36 Timing Characteristics (Nominal 5.0 V Operation)(Worst-Case Commercial Conditions, $V_{CCA} = 4.75\text{ V}$, $T_J = 70^{\circ}\text{C}$)	75
Table 45	A42MX36 Timing Characteristics (Nominal 3.3 V Operation) (Worst-Case Commercial Conditions,	

2.4 Plastic Device Resources

Table 2 • Plastic Device Resources

Device	User I/Os											
	PLCC 44-Pin	PLCC 68-Pin	PLCC 84-Pin	PQFP 100-Pin	PQFP 144- Pin	PQFP 160-Pin	PQFP 208- Pin	PQFP 240-Pin	VQFP 80-Pin	VQFP 100- Pin	TQFP 176- Pin	PBGA 272- Pin
A40MX02	34	57	–	57	–	–	–	–	57	–	–	–
A40MX04	34	57	69	69	–	–	–	–	69	–	–	–
A42MX09	–	–	72	83	95	101	–	–	–	83	104	–
A42MX16	–	–	72	83	–	125	140	–	–	83	140	–
A42MX24	–	–	72	–	–	125	176	–	–	–	150	–
A42MX36	–	–	–	–	–	–	176	202	–	–	–	202

Note: Package Definitions: PLCC = Plastic Leaded Chip Carrier, PQFP = Plastic Quad Flat Pack, TQFP = Thin Quad Flat Pack, VQFP = Very Thin Quad Flat Pack, PBGA = Plastic Ball Grid Array

2.5 Ceramic Device Resources

Table 3 • Ceramic Device Resources

Device	User I/Os			
	CPGA 132-Pin	CQFP 172-Pin	CQFP 208-Pin	CQFP 256-Pin
A42MX09	95			
A42MX16		131		
A42MX36			176	202

Note: Package Definitions: CQFP = Ceramic Quad Flat Pack

3 40MX and 42MX FPGAs

3.1 General Description

Microsemi's 40MX and 42MX families offer a cost-effective design solution at 5V. The MX devices are single-chip solutions and provide high performance while shortening the system design and development cycle. MX devices can integrate and consolidate logic implemented in multiple PALs, CPLDs, and FPGAs. Example applications include high-speed controllers and address decoding, peripheral bus interfaces, DSP, and co-processor functions.

The MX device architecture is based on Microsemi's patented antifuse technology implemented in a 0.45µm triple-metal CMOS process. With capacities ranging from 3,000 to 54,000 system gates, the MX devices provide performance up to 250 MHz, are live on power-up and have one-fifth the standby power consumption of comparable FPGAs. MX FPGAs provide up to 202 user I/Os and are available in a wide variety of packages and speed grades.

A42MX24 and A42MX36 devices also feature multiPlex I/Os, which support mixed-voltage systems, enable programmable PCI, deliver high-performance operation at both 5.0V and 3.3V, and provide a low-power mode. The devices are fully compliant with the PCI local bus specification (version 2.1). They deliver 200 MHz on-chip operation and 6.1 ns clock-to-output performance.

The 42MX24 and 42MX36 devices include system-level features such as IEEE Standard 1149.1 (JTAG) Boundary Scan Testing and fast wide-decode modules. In addition, the A42MX36 device offers dual-port SRAM for implementing fast FIFOs, LIFOs, and temporary data storage. The storage elements can efficiently address applications requiring wide data path manipulation and can perform transformation functions such as those required for telecommunications, networking, and DSP.

All MX devices are fully tested over automotive and military temperature ranges. In addition, the largest member of the family, the A42MX36, is available in both CQ208 and CQ256 ceramic packages screened to MIL-STD-883 levels. For easy prototyping and conversion from plastic to ceramic, the CQ208 and PQ208 devices are pin-compatible.

3.2 MX Architectural Overview

The MX devices are composed of fine-grained building blocks that enable fast, efficient logic designs. All devices within these families are composed of logic modules, I/O modules, routing resources and clock networks, which are the building blocks for fast logic designs. In addition, the A42MX36 device contains embedded dual-port SRAM modules, which are optimized for high-speed data path functions such as FIFOs, LIFOs and scratch pad memory. A42MX24 and A42MX36 also contain wide-decode modules.

3.2.1 Logic Modules

The 40MX logic module is an eight-input, one-output logic circuit designed to implement a wide range of logic functions with efficient use of interconnect routing resources.(see the following figure).

The logic module can implement the four basic logic functions (NAND, AND, OR and NOR) in gates of two, three, or four inputs. The logic module can also implement a variety of D-latches, exclusivity functions, AND-ORs and OR-ANDs. No dedicated hard-wired latches or flip-flops are required in the array; latches and flip-flops can be constructed from logic modules whenever required in the application.

reliability. Devices should not be operated outside the recommended operating conditions.

Table 21 • Recommended Operating Conditions

Parameter	Commercial	Industrial	Military	Units
Temperature Range*	0 to +70	–40 to +85	–55 to +125	°C
VCCA	4.75 to 5.25	4.5 to 5.5	4.5 to 5.5	V
VCCI	3.14 to 3.47	3.0 to 3.6	3.0 to 3.6	V

Note: *Ambient temperature (T_A) is used for commercial and industrial grades; case temperature (T_C) is used for military grades.

Table 23 • DC Specification (5.0 V PCI Signaling)¹

Symbol	Parameter	Condition	PCI		MX		Units
			Min.	Max.	Min.	Max.	
C _{IN}	Input Pin Capacitance			10	—	10	pF
C _{CLK}	CLK Pin Capacitance		5	12	—	10	pF
L _{PIN}	Pin Inductance			20	—	< 8 nH ⁴	nH

1. PCI Local Bus Specification, Version 2.1, Section 4.2.1.1.

2. Maximum rating for VCCI –0.5 V to 7.0 V

3. VIH(Min) is 2.4V for A42MX36 family. This applies only to VCCI of 5V and is not applicable to VCCI of 3.3V.

4. Dependent upon the chosen package. PCI recommends QFP and BGA packaging to reduce pin inductance and capacitance.

Table 24 • AC Specifications (5.0V PCI Signaling)*

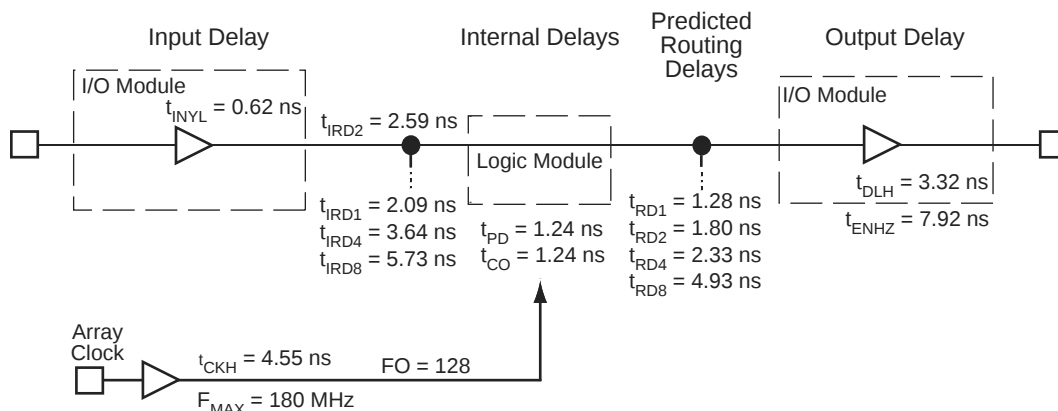
Symbol	Parameter	Condition	PCI		MX		Units
			Min.	Max.	Min.	Max.	
ICL	Low Clamp Current	$-5 < V_{IN} \leq -1$	$-25 + (V_{IN} + 1) / 0.015$		–60	–10	mA
Slew (r)	Output Rise Slew Rate	0.4 V to 2.4 V load	1	5	1.8	2.8	V/ns
Slew (f)	Output Fall Slew Rate	2.4 V to 0.4 V load	1	5	2.8	4.3	V/ns

Note: *PCI Local Bus Specification, Version 2.1, Section 4.2.1.2.

3.10 Timing Models

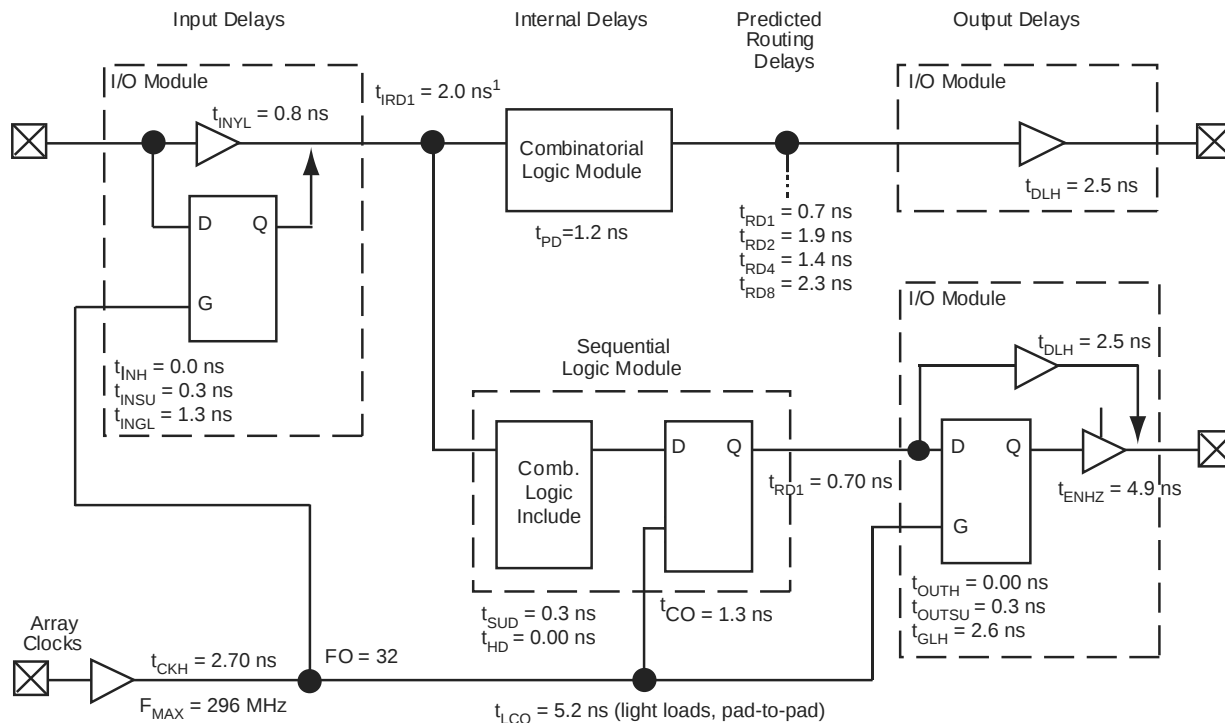
The following figures show various timing models.

Figure 17 • 40MX Timing Model*



Note: Values are shown for 40MX –3 speed devices at 5.0 V worst-case commercial conditions.

Figure 18 • 42MX Timing Model



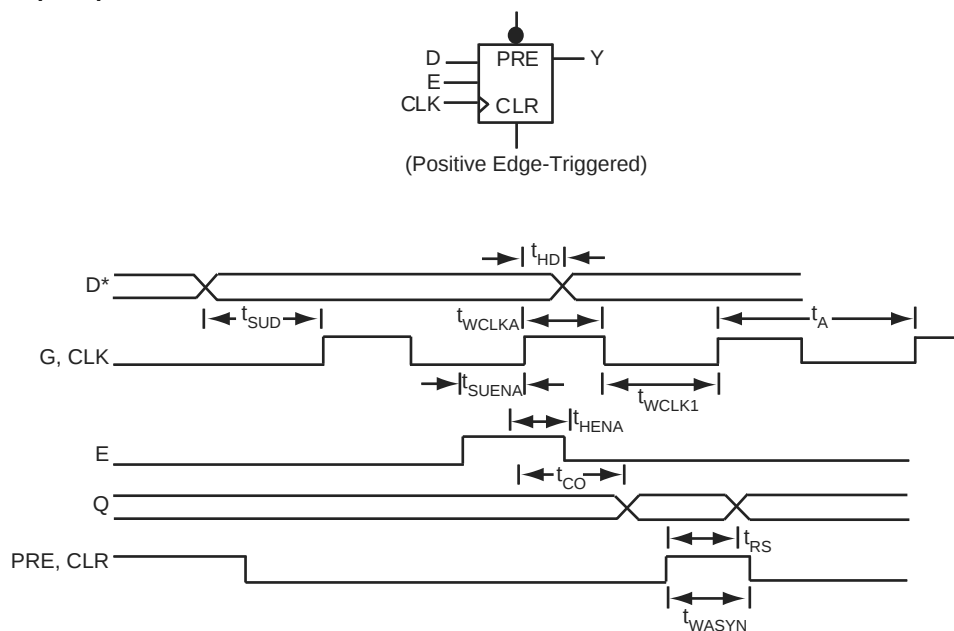
Note: 1. Input module predicted routing delay

Note: 2. Values are shown for A42MX09 –3 at 5.0 V worst-case commercial conditions.

3.10.2 Sequential Module Timing Characteristics

The following figure shows sequential module timing characteristics.

Figure 25 • Flip-Flops and Latches



Note: *D represents all data functions involving A, B, and S for multiplexed flip-flops.

3.10.3 Sequential Timing Characteristics

The following figures show sequential timing characteristics.

Figure 26 • Input Buffer Latches

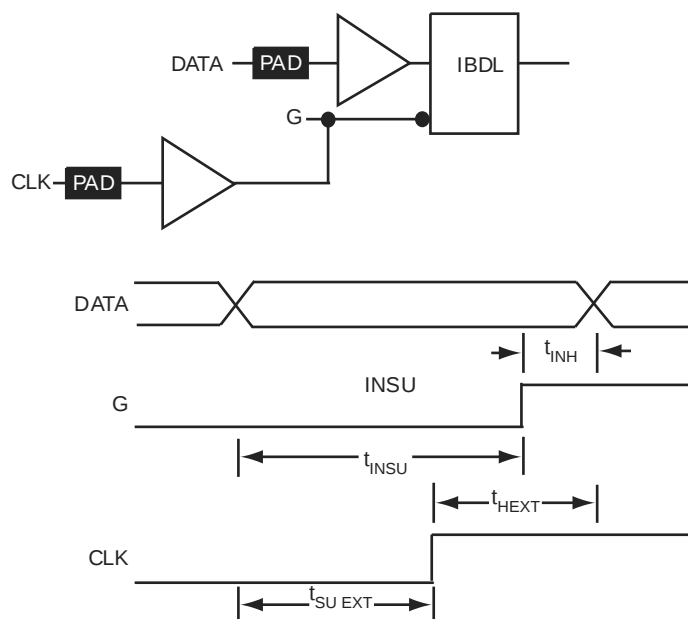


Table 34 • A40MX02 Timing Characteristics (Nominal 5.0 V Operation) (continued)
(Worst-Case Commercial Conditions, VCC = 4.75 V, T_J = 70°C)

Parameter / Description			–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Input Module Propagation Delays													
t _{INYH}	Pad-to-Y HIGH		0.7		0.8		0.9		1.1		1.5		ns
t _{INYL}	Pad-to-Y LOW		0.6		0.7		0.8		1.0		1.3		ns
Input Module Predicted Routing Delays ¹													
t _{IRD1}	FO = 1 Routing Delay		2.1		2.4		2.2		3.2		4.5		ns
t _{IRD2}	FO = 2 Routing Delay		2.6		3.0		3.4		4.0		5.6		ns
t _{IRD3}	FO = 3 Routing Delay		3.1		3.6		4.1		4.8		6.7		ns
t _{IRD4}	FO = 4 Routing Delay		3.6		4.2		4.8		5.6		7.8		ns
t _{IRD8}	FO = 8 Routing Delay		5.7		6.6		7.5		8.8		12.4		ns
Global Clock Network													
t _{CKH}	Input Low to HIGH	FO = 16 FO = 128	4.6 4.6		5.3 5.3		6.0 6.0		7.0 7.0		9.8 9.8		ns
t _{CKL}	Input High to LOW	FO = 16 FO = 128	4.8 4.8		5.6 5.6		6.3 6.3		7.4 7.4		10.4 10.4		ns
t _{PWH}	Minimum Pulse Width HIGH	FO = 16 FO = 128	2.2 2.4	2.6 2.7		2.9 3.1		3.4 3.6		4.8 5.1		ns	
t _{PWL}	Minimum Pulse Width LOW	FO = 16 FO = 128	2.2 2.4	2.6 2.7		2.9 3.01		3.4 3.6		4.8 5.1		ns	
t _{CKSW}	Maximum Skew	FO = 16 FO = 128	0.4 0.5		0.5 0.6		0.5 0.7		0.6 0.8		0.8 1.2		ns
t _P	Minimum Period	FO = 16 FO = 128	4.7 4.8	5.4 5.6		6.1 6.3		7.2 7.5		10.0 10.4		ns	
f _{MAX}	Maximum Frequency	FO = 16 FO = 128	188 181		175 168		160 154		139 134		83 80		MHz

Table 38 • A42MX09 Timing Characteristics (Nominal 5.0 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 4.75 V, T_J = 70°C)

Parameter / Description		–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
TTL Output Module Timing ⁵												
t _{DLH}	Data-to-Pad HIGH		2.5		2.7		3.1		3.6		5.1	ns
t _{DHL}	Data-to-Pad LOW		2.9		3.2		3.6		4.3		6.0	ns
t _{ENZH}	Enable Pad Z to HIGH		2.6		2.9		3.3		3.9		5.5	ns
t _{ENZL}	Enable Pad Z to LOW		2.9		3.2		3.7		4.3		6.1	ns
t _{ENHZ}	Enable Pad HIGH to Z		4.9		5.4		6.2		7.3		10.2	ns
t _{ENLZ}	Enable Pad LOW to Z		5.3		5.9		6.7		7.9		11.1	ns
t _{GLH}	G-to-Pad HIGH		2.6		2.9		3.3		3.8		5.3	ns
t _{GHL}	G-to-Pad LOW		2.6		2.9		3.3		3.8		5.3	ns
t _{LSU}	I/O Latch Set-Up	0.5		0.5		0.6		0.7		1.0		ns
t _{LH}	I/O Latch Hold	0.0		0.0		0.0		0.0		0.0		ns
t _{LCO}	I/O Latch Clock-to-Out (Pad-to-Pad), 64 Clock Loading		5.2		5.8		6.6		7.7		10.8	ns
t _{ACO}	Array Clock-to-Out (Pad-to-Pad), 64 Clock Loading		7.4		8.2		9.3		10.9		15.3	ns
d _{TLH}	Capacity Loading, LOW to HIGH		0.03		0.03		0.03		0.04		0.06	ns/pF
d _{THL}	Capacity Loading, HIGH to LOW		0.04		0.04		0.04		0.05		0.07	ns/pF

Table 45 • A42MX36 Timing Characteristics (Nominal 3.3 V Operation) (continued)(Worst-Case Commercial Conditions, VCCA = 3.0 V, T_J = 70°C)

Parameter / Description		–3 Speed		–2 Speed		–1 Speed		Std Speed		–F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Synchronous SRAM Operations (continued)												
t _{ADH}	Address/Data Hold Time	0.0		0.0		0.0		0.0		0.0		ns
t _{RENSU}	Read Enable Set-Up	0.9		1.0		1.1		1.3		1.8		ns
t _{RENH}	Read Enable Hold	4.8		5.3		6.0		7.0		9.8		ns
t _{WENSU}	Write Enable Set-Up	3.8		4.2		4.8		5.6		7.8		ns
t _{WENH}	Write Enable Hold	0.0		0.0		0.0		0.0		0.0		ns
t _{BENS}	Block Enable Set-Up	3.9		4.3		4.9		5.7		8.0		ns
t _{BENH}	Block Enable Hold	0.0		0.0		0.0		0.0		0.0		ns
Asynchronous SRAM Operations												
t _{RPD}	Asynchronous Access Time		11.3		12.6		14.3		16.8		23.5	ns
t _{RDADV}	Read Address Valid	12.3		13.7		15.5		18.2		25.5		ns
t _{ADSU}	Address/Data Set-Up Time	2.3		2.5		2.8		3.4		4.8		ns
t _{ADH}	Address/Data Hold Time	0.0		0.0		0.0		0.0		0.0		ns
t _{RENSUA}	Read Enable Set-Up to Address Valid	0.9		1.0		1.1		1.3		1.8		ns
t _{RENHA}	Read Enable Hold	4.8		5.3		6.0		7.0		9.8		ns
t _{WENSU}	Write Enable Set-Up	3.8		4.2		4.8		5.6		7.8		ns
t _{WENH}	Write Enable Hold	0.0		0.0		0.0		0.0		0.0		ns
t _{DOH}	Data Out Hold Time		1.8		2.0		2.1		2.5		3.5	ns
Input Module Propagation Delays												
t _{INPY}	Input Data Pad-to-Y		1.4		1.6		1.8		2.1		3.0	ns
t _{INGO}	Input Latch Gate-to-Output		2.0		2.2		2.5		2.9		4.1	ns
t _{INH}	Input Latch Hold	0.0		0.0		0.0		0.0		0.0		ns
t _{INSU}	Input Latch Set-Up	0.7		0.7		0.8		1.0		1.4		ns
t _{ILA}	Latch Active Pulse Width	6.5		7.3		8.2		9.7		13.5		ns

Input, output, tristate or bidirectional buffer. Input and output levels are compatible with standard TTL and CMOS specifications. Unused I/Os pins are configured by the Designer software as shown in Table 46, page 84.

Table 46 • Configuration of Unused I/Os

Device	Configuration
A40MX02, A40MX04	Pulled LOW
A42MX09, A42MX16	Pulled LOW
A42MX24, A42MX36	Tristated

In all cases, it is recommended to tie all unused MX I/O pins to LOW on the board. This applies to all dual-purpose pins when configured as I/Os as well.

LP, Low Power Mode

Controls the low power mode of all 42MX devices. The device is placed in the low power mode by connecting the LP pin to logic HIGH. In low power mode, all I/Os are tristated, all input buffers are turned OFF, and the core of the device is turned OFF. To exit the low power mode, the LP pin must be set LOW. The device enters the low power mode 800 ns after the LP pin is driven to a logic HIGH. It will resume normal operation in 200 μ s after the LP pin is driven to a logic LOW.

MODE, Mode

Controls the use of multifunction pins (DCLK, PRA, PRB, SDI, TDO). The MODE pin is held HIGH to provide verification capability. The MODE pin should be terminated to GND through a 10k Ω resistor so that the MODE pin can be pulled HIGH when required.

NC, No Connection

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

PRA, I/O

PRB, I/OProbe A/B

The Probe pin is used to output data from any user-defined design node within the device. Each diagnostic pin can be used in conjunction with the other probe pin to allow real-time diagnostic output of any signal path within the device. The Probe pin can be used as a user-defined I/O when verification has been completed. The pin's probe capabilities can be permanently disabled to protect programmed design confidentiality. The Probe pin is accessible when the MODE pin is HIGH. This pin functions as an I/O when the MODE pin is LOW.

QCLKA/B/C/D, I/O Quadrant Clock

Quadrant clock inputs for A42MX36 devices. When not used as a register control signal, these pins can function as user I/Os.

SDI, I/O Serial Data Input

Serial data input for diagnostic probe and device programming. SDI is active when the MODE pin is HIGH. This pin functions as an I/O when the MODE pin is LOW.

SDO, I/O Serial Data Output

Serial data output for diagnostic probe and device programming. SDO is active when the MODE pin is HIGH. This pin functions as an I/O when the MODE pin is LOW. SDO is available for 42MX devices only.

When Silicon Explorer II is being used, SDO will act as an output while the "checksum" command is run. It will return to user I/O when "checksum" is complete.

TCK, I/O Test Clock

Figure 43 • PQ160

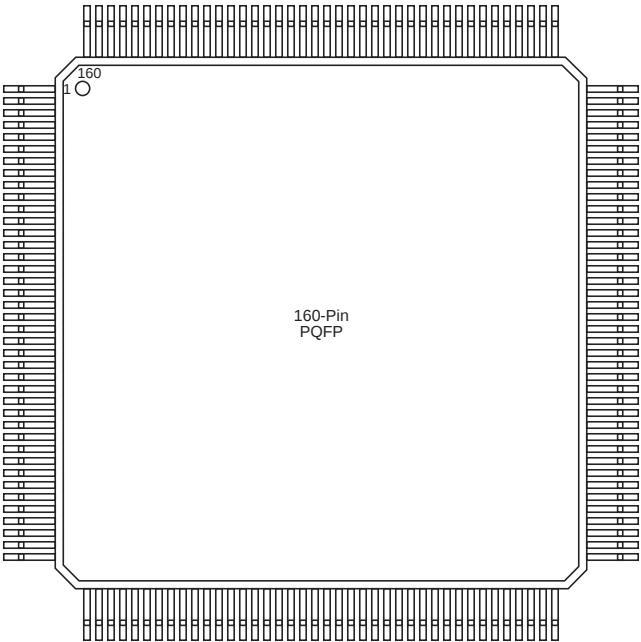


Table 52 • PQ160

PQ160			
Pin Number	A42MX09 Function	A42MX16 Function	A42MX24 Function
1	I/O	I/O	I/O
2	DCLK, I/O	DCLK, I/O	DCLK, I/O
3	NC	I/O	I/O
4	I/O	I/O	WD, I/O
5	I/O	I/O	WD, I/O
6	NC	VCCI	VCCI
7	I/O	I/O	I/O
8	I/O	I/O	I/O
9	I/O	I/O	I/O
10	NC	I/O	I/O
11	GND	GND	GND
12	NC	I/O	I/O
13	I/O	I/O	WD, I/O
14	I/O	I/O	WD, I/O
15	I/O	I/O	I/O
16	PRB, I/O	PRB, I/O	PRB, I/O
17	I/O	I/O	I/O
18	CLKB, I/O	CLKB, I/O	CLKB, I/O
19	I/O	I/O	I/O
20	VCCA	VCCA	VCCA

Table 52 • PQ160

PQ160			
Pin Number	A42MX09 Function	A42MX16 Function	A42MX24 Function
58	VCCI	VCCI	VCCI
59	GND	GND	GND
60	VCCA	VCCA	VCCA
61	LP	LP	LP
62	I/O	I/O	TCK, I/O
63	I/O	I/O	I/O
64	GND	GND	GND
65	I/O	I/O	I/O
66	I/O	I/O	I/O
67	I/O	I/O	I/O
68	I/O	I/O	I/O
69	GND	GND	GND
70	NC	I/O	I/O
71	I/O	I/O	I/O
72	I/O	I/O	I/O
73	I/O	I/O	I/O
74	I/O	I/O	I/O
75	NC	I/O	I/O
76	I/O	I/O	I/O
77	NC	I/O	I/O
78	I/O	I/O	I/O
79	NC	I/O	I/O
80	GND	GND	GND
81	I/O	I/O	I/O
82	SDO, I/O	SDO, I/O	SDO, TDO, I/O
83	I/O	I/O	WD, I/O
84	I/O	I/O	WD, I/O
85	I/O	I/O	I/O
86	NC	VCCI	VCCI
87	I/O	I/O	I/O
88	I/O	I/O	WD, I/O
89	GND	GND	GND
90	NC	I/O	I/O
91	I/O	I/O	I/O
92	I/O	I/O	I/O
93	I/O	I/O	I/O
94	I/O	I/O	I/O

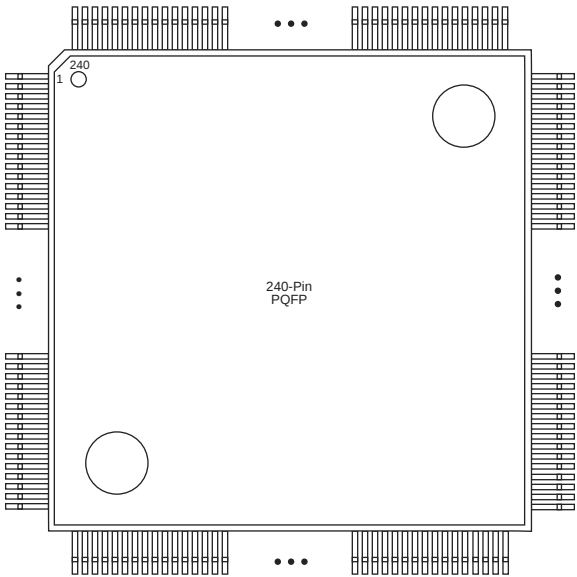
Table 53 • PQ208

PQ208			
Pin Number	A42MX16 Function	A42MX24 Function	A42MX36 Function
132	VCCI	VCCI	VCCI
133	VCCA	VCCA	VCCA
134	I/O	I/O	I/O
135	I/O	I/O	I/O
136	VCCA	VCCA	VCCA
137	I/O	I/O	I/O
138	I/O	I/O	I/O
139	I/O	I/O	I/O
140	I/O	I/O	I/O
141	NC	I/O	I/O
142	I/O	I/O	I/O
143	I/O	I/O	I/O
144	I/O	I/O	I/O
145	I/O	I/O	I/O
146	NC	I/O	I/O
147	NC	I/O	I/O
148	NC	I/O	I/O
149	NC	I/O	I/O
150	GND	GND	GND
151	I/O	I/O	I/O
152	I/O	I/O	I/O
153	I/O	I/O	I/O
154	I/O	I/O	I/O
155	I/O	I/O	I/O
156	I/O	I/O	I/O
157	GND	GND	GND
158	I/O	I/O	I/O
159	SDI, I/O	SDI, I/O	SDI, I/O
160	I/O	I/O	I/O
161	I/O	WD, I/O	WD, I/O
162	I/O	WD, I/O	WD, I/O
163	I/O	I/O	I/O
164	VCCI	VCCI	VCCI
165	NC	I/O	I/O
166	NC	I/O	I/O
167	I/O	I/O	I/O
168	I/O	WD, I/O	WD, I/O

Table 53 • PQ208

PQ208			
Pin Number	A42MX16 Function	A42MX24 Function	A42MX36 Function
206	I/O	I/O	I/O
207	DCLK, I/O	DCLK, I/O	DCLK, I/O
208	I/O	I/O	I/O

Figure 45 • PQ240



Note: This figure shows the 240-Pin PQFP Package top view.

Table 54 • PQ240

PQ240	
Pin Number	A42MX36 Function
1	I/O
2	DCLK, I/O
3	I/O
4	I/O
5	I/O
6	WD, I/O
7	WD, I/O
8	VCCI
9	I/O
10	I/O
11	I/O
12	I/O
13	I/O
14	I/O

Table 56 • VQ100

VQ100		
Pin Number	A42MX09 Function	A42MX16 Function
57	I/O	I/O
58	I/O	I/O
59	I/O	I/O
60	I/O	I/O
61	I/O	I/O
62	LP	LP
63	VCCA	VCCA
64	VCCI	VCCI
65	VCCA	VCCA
66	I/O	I/O
67	I/O	I/O
68	I/O	I/O
69	I/O	I/O
70	GND	GND
71	I/O	I/O
72	I/O	I/O
73	I/O	I/O
74	I/O	I/O
75	I/O	I/O
76	I/O	I/O
77	SDI, I/O	SDI, I/O
78	I/O	I/O
79	I/O	I/O
80	I/O	I/O
81	I/O	I/O
82	GND	GND
83	I/O	I/O
84	I/O	I/O
85	PRA, I/O	PRA, I/O
86	I/O	I/O
87	CLKA, I/O	CLKA, I/O
88	VCCA	VCCA
89	I/O	I/O
90	CLKB, I/O	CLKB, I/O
91	I/O	I/O
92	PRB, I/O	PRB, I/O

Table 56 • VQ100

VQ100		
Pin Number	A42MX09 Function	A42MX16 Function
93	I/O	I/O
94	GND	GND
95	I/O	I/O
96	I/O	I/O
97	I/O	I/O
98	I/O	I/O
99	I/O	I/O
100	DCLK, I/O	DCLK, I/O

Figure 48 • TQ176

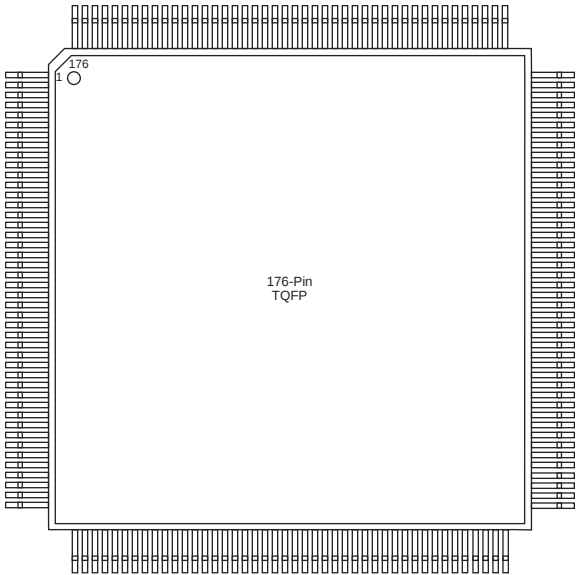


Table 57 • TQ176

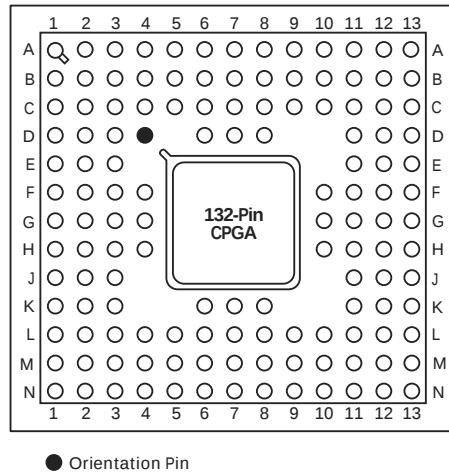
TQ176			
Pin Number	A42MX09 Function	A42MX16 Function	A42MX24 Function
1	GND	GND	GND
2	MODE	MODE	MODE
3	I/O	I/O	I/O
4	I/O	I/O	I/O
5	I/O	I/O	I/O
6	I/O	I/O	I/O
7	I/O	I/O	I/O
8	NC	NC	I/O
9	I/O	I/O	I/O

Table 58 • CQ208

CQ208	
Pin Number	A42MX36 Function
1	GND
2	VCCA
3	MODE
4	I/O
5	I/O
6	I/O
7	I/O
8	I/O
9	I/O
10	I/O
11	I/O
12	I/O
13	I/O
14	I/O
15	I/O
16	I/O
17	VCCA
18	I/O
19	I/O
20	I/O
21	I/O
22	GND
23	I/O
24	I/O
25	I/O
26	I/O
27	GND
28	VCCI
29	VCCA
30	I/O
31	I/O
32	VCCA
33	I/O
34	I/O
35	I/O
36	I/O

Table 60 • BG272

BG272	
Pin Number	A42MX36 Function
Y13	I/O
Y14	I/O
Y15	I/O
Y16	I/O
Y17	I/O
Y18	WD, I/O
Y19	GND
Y20	GND

Figure 52 • PG132**Table 61 • PG132**

PG132	
Pin Number	A42MX09 Function
–	PMPOUT
B2	I/O
A1	MODE
B1	I/O
D3	I/O
C2	I/O
C1	I/O
D2	I/O
D1	I/O
E2	I/O
E1	I/O
F3	I/O

Figure 53 • CQ172**Table 62 • CQ172**

CQ172	
Pin Number	A42MX16 Function
1	MODE
2	I/O
3	I/O
4	I/O
5	I/O
6	I/O
7	GND
8	I/O
9	I/O
10	I/O
11	I/O
12	VCC
13	I/O
14	I/O
15	I/O
16	I/O
17	GND
18	I/O
19	I/O
20	I/O